SPECIFICATION AMENDMENTS:

Please amend the specification as follows:

Before the first line in the application, please insert --This is a Divisional of U.S. Application No.: 10/125,444, filed April 19, 2002.--

Page 1, line 8, through line 23, please amend the current paragraphs as follows:

--A conventional IC packaging is ~~a method~~ used for protecting an IC body from external substances and mounting on a circuit board. In recent years, because IC products have an even wider range of applications, and material, size and configuration of packages have become diversified, and as the demand to mount a larger number of pins at an even higher density has increased, the demand to add higher values to the package itself has increased even more.

One such package configuration is a TCP (tape carrier package). A tape carrier herein is a semiconductor device fabricated in the following manner. A device hole is first formed in a flexible base tape, leads (wiring patterns) are formed by, for example, photolithography, and then a solder resist is formed to protect the leads. The TCP is a package in which semiconductor elements are mounted on the tape carrier and sealed by, for example, a resin. A package in which semiconductor element(s) are mounted on a tape carrier but are not sealed by a molding is referred to as a structure.--

Page 12, line 12, through Page 13, line 7, please amend the current paragraph as follows:

--A base film 101 is made of a polyimide, for example. Sprocket holes 102 are formed on the base film 101 to convey the same. Protruding electrodes 111 are provided on a lower semiconductor element 110. The electrodes 111 are connected to terminals 103 via inner lead portions 105. Protruding electrodes 108 are provided on an upper semiconductor element 107. The electrodes 108 are connected to other terminals 103 via inner lead portions 104. The terminals 103 are connected to external substrates. The width of the inner lead portion 104 or 105 decreases at the portion where it is connected to the electrode 108 or 111 to make space between adjacent leads. The inner lead portion 105 is shorter than the inner lead portion 104. The upper and the lower semiconductor elements 107 and 110 are substantially square-shaped, and the upper semiconductor element 107 is smaller than the lower semiconductor element 110. The tape carrier of the present embodiment may be applied to upper and lower semiconductor elements 107 and 110 of any shape, such as rectangular, by changing an arrangement of the inner lead portions formed on the base film 101. The upper semiconductor element 107 is stacked on and adhered to the lower semiconductor element 110 using an adhesive 109.--

Page 14, line 5, through line 19, please amend the current paragraph as follows:

--End portions of the inner lead portions 104 and 105, which are opposite to the end portions where the inner lead portions 104 and 105 are connected to the electrodes 108 and 111, are formed as the terminals 103. The terminals 103 are connected to external circuits. The base film has a common hole formed at an edge thereof. The ends of the lead portions terminate at this common hole. The terminals 103 and the inner lead

portions 104 and 105 are plated with Sn, Au or solder. These copper wiring patterns composed of the inner lead portions 104 and 105 are nipped between a solder resist 106 and the base film 101 and shielded from the outside. A sealing resin 112 seals the whole of upper semiconductor element 107, side surfaces of the lower semiconductor element 110, the inner lead portions 104 and 105, a part of the solder resist 106 and a part of the base film 101 to protect the whole package. In this structure, because the bottom surface of the lower semiconductor element 110 is not covered with the sealing resin 112, the TCP on the whole can be made thinner than conventional TCPs.--